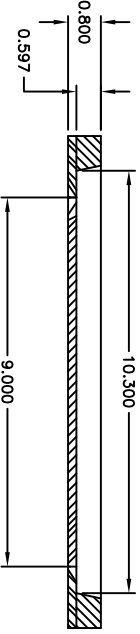
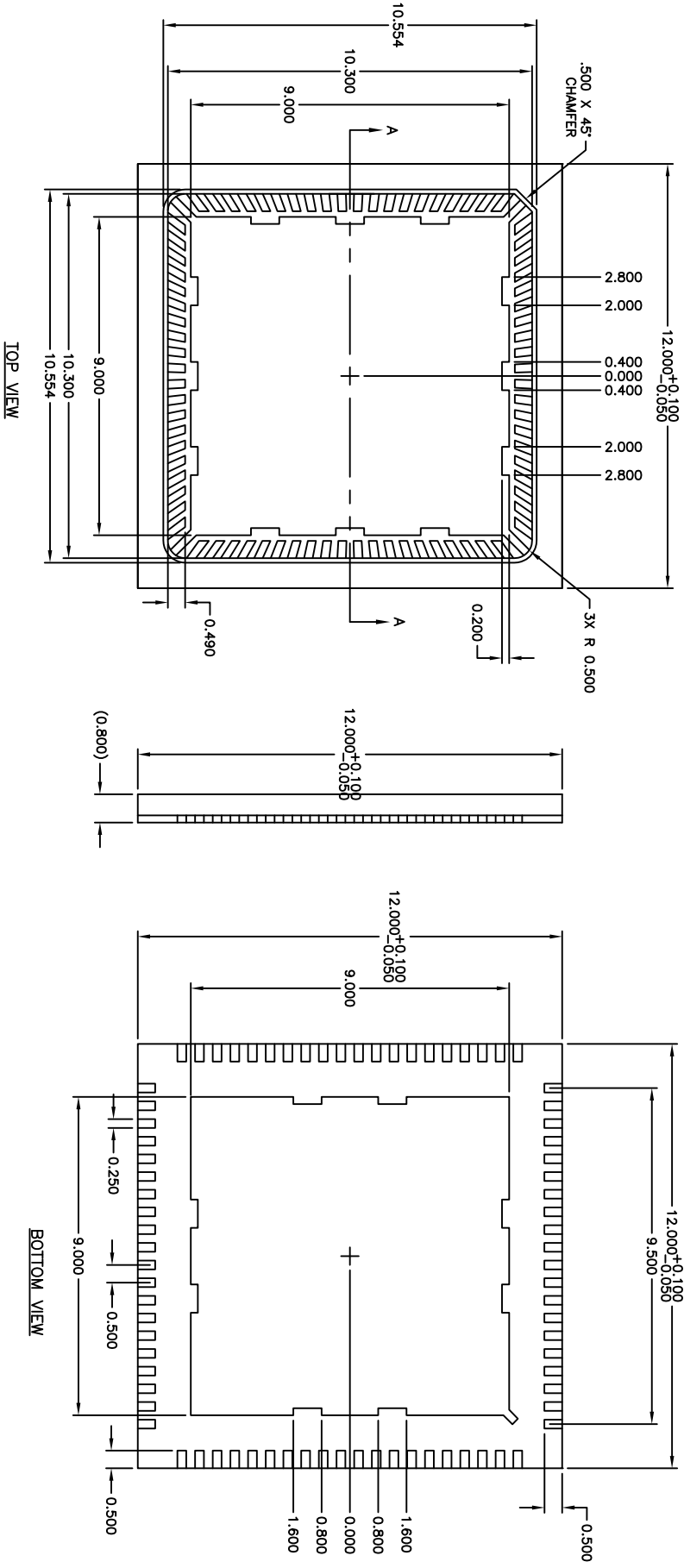


SEMPAC REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.MORRIS
11038	6/22/12	PRODUCTION RELEASE	



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. LEAD THICKNESS: 0.2030 ±.0076
 5. FRAME THICKNESS: 0.2030 ±.0076
 6. DIE PAD: 9.000mm x 9.000mm.



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE: X.XXXX ± ---
X.XX ± 0.015 X.XXX ± ---
X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	VSK	DATE	6/22/12
APP BY	P. FLASKERUD	DATE	6/22/12

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SEMPAC, INC.
 Open-Pak™ Technologies
 www.sempac.com
 588 E. WEDDELL DRIVE, SUITE 5
 SUNNYSVALE, CALIFORNIA 94089
 PHONE: (408) 400-9002 FAX: (408) 400-9006

80 LEAD 12mm X 12mm
 MLP Open-Pak™

SIZE	PART NO.	REV
A	MLP12X12-80-OP-02	1
SCALE	NONE	
CAD FILE	MLP12X12-80-OP-02-R1	
SHEET	1 OF 1	